

Layer	Name	Material	Thickness	Constant	Board Layer Stack
	Top Overlay				
	Top Solder	SM-001	0.025mm	4	
1	Top Layer	CF-004	0.018mm		
	Dielectric-1	PP-006	0.220mm	4.1	
2	GND-1	CF-004	0.035mm		
	Core-1	Core-035	0.350mm	4.7	
3	INT-SIG-1	CF-004	0.035mm		
	Dielectric-2	PP-006	0.220mm	4.1	
4	INT-SIG-2	CF-004	0.035mm		
	Core-2	Core-035	0.350mm	4.7	
5	GND-2	CF-004	0.035mm		
	Dielectric-3	PP-006	0.220mm	4.1	
6	Bottom Layer	CF-004	0.018mm		
	Bottom Solder	SM-001	0.025mm	4	
	Bottom Overlay				

Total board thickness: 1.586mm

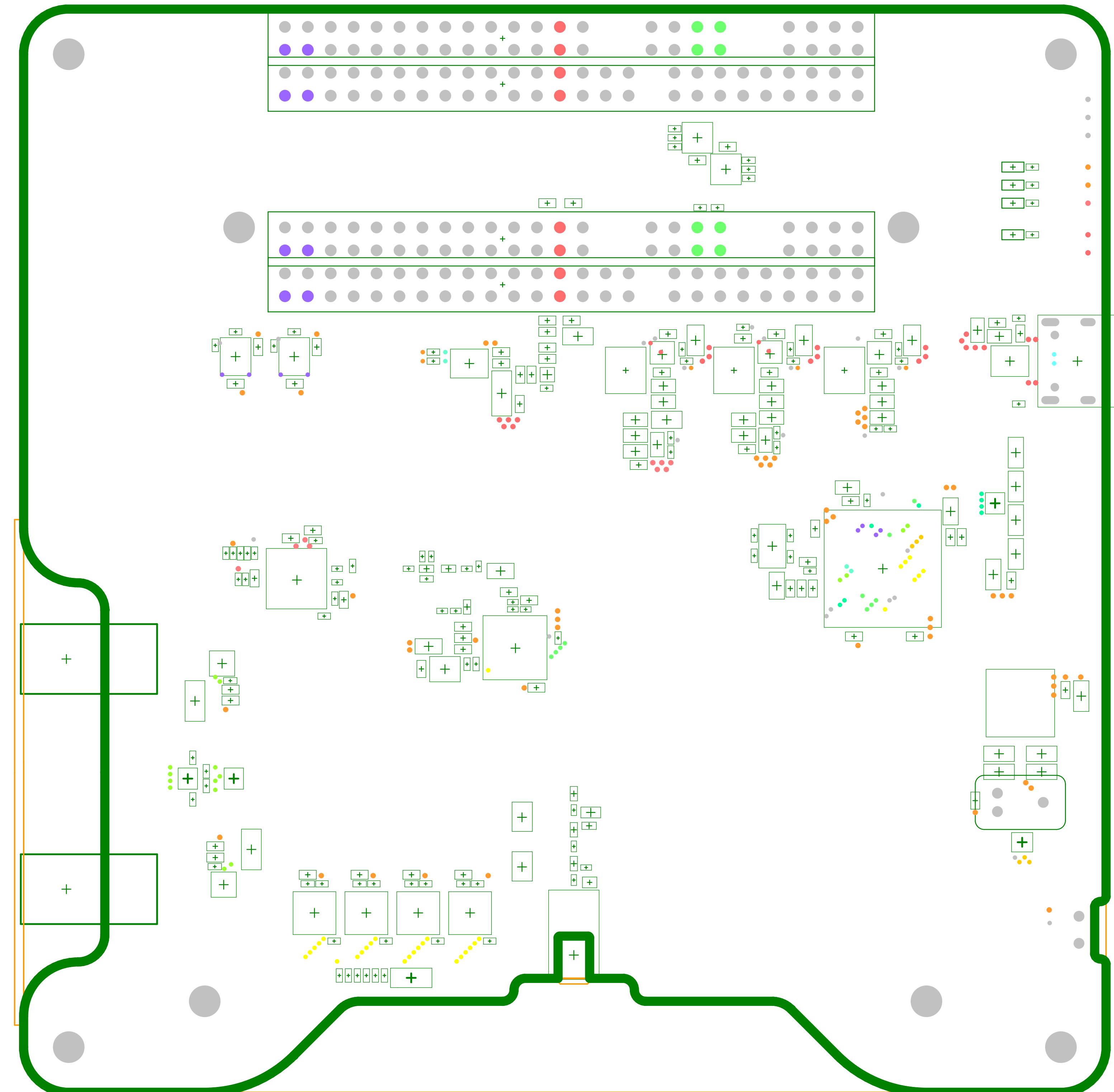
Pluton UPV	
Project: Estigia LoRa Comms PL - mPCIe SoM	
Layer: Board Shape Component Guard Dimension	
Component Guard	
Engineer: Juan Del Pino Mena	
Date: 03/09/2024	Revision: 0.3
Size: A4	

A

B

C

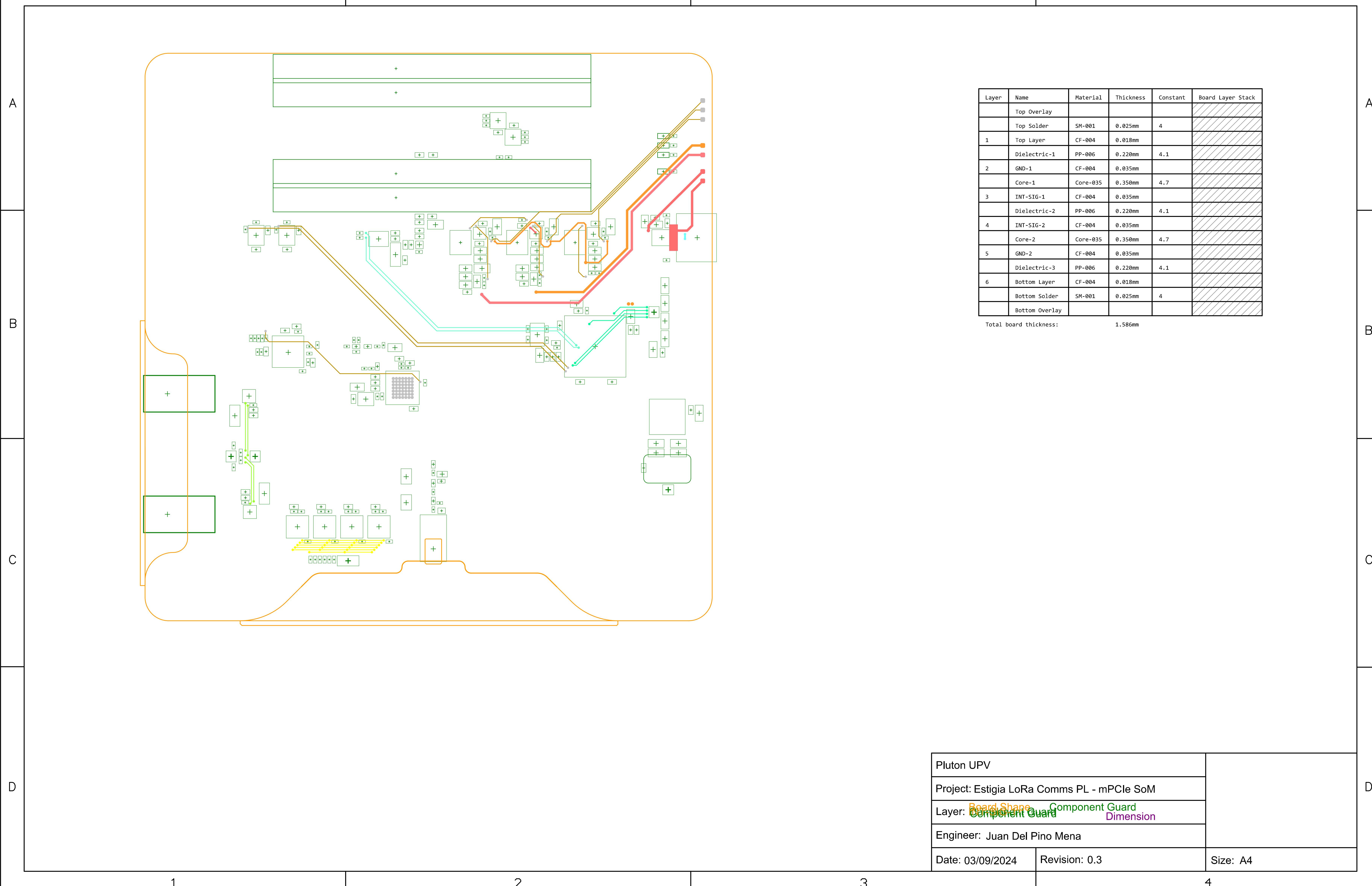
D



Layer	Name	Material	Thickness	Constant	Board Layer Stack
	Top Overlay				
	Top Solder	SM-001	0.025mm	4	
1	Top Layer	CF-004	0.018mm		
	Dielectric-1	PP-006	0.220mm	4.1	
2	GND-1	CF-004	0.035mm		
	Core-1	Core-035	0.350mm	4.7	
3	INT-SIG-1	CF-004	0.035mm		
	Dielectric-2	PP-006	0.220mm	4.1	
4	INT-SIG-2	CF-004	0.035mm		
	Core-2	Core-035	0.350mm	4.7	
5	GND-2	CF-004	0.035mm		
	Dielectric-3	PP-006	0.220mm	4.1	
6	Bottom Layer	CF-004	0.018mm		
	Bottom Solder	SM-001	0.025mm	4	
	Bottom Overlay				

Total board thickness: 1.586mm

Pluton UPV	
Project: Estigia LoRa Comms PL - mPCIe SoM	
Layer: Board Shape Component Guard Dimension	
Engineer: Juan Del Pino Mena	
Date: 03/09/2024	Revision: 0.3
	Size: A4





Layer	Name	Material	Thickness	Constant	Board Layer Stack
	Top Overlay				
	Top Solder	SM-001	0.025mm	4	
1	Top Layer	CF-004	0.018mm		
	Dielectric-1	PP-006	0.220mm	4.1	
2	GND-1	CF-004	0.035mm		
	Core-1	Core-035	0.350mm	4.7	
3	INT-SIG-1	CF-004	0.035mm		
	Dielectric-2	PP-006	0.220mm	4.1	
4	INT-SIG-2	CF-004	0.035mm		
	Core-2	Core-035	0.350mm	4.7	
5	GND-2	CF-004	0.035mm		
	Dielectric-3	PP-006	0.220mm	4.1	
6	Bottom Layer	CF-004	0.018mm		
	Bottom Solder	SM-001	0.025mm	4	
	Bottom Overlay				

Total board thickness: 1.586mm

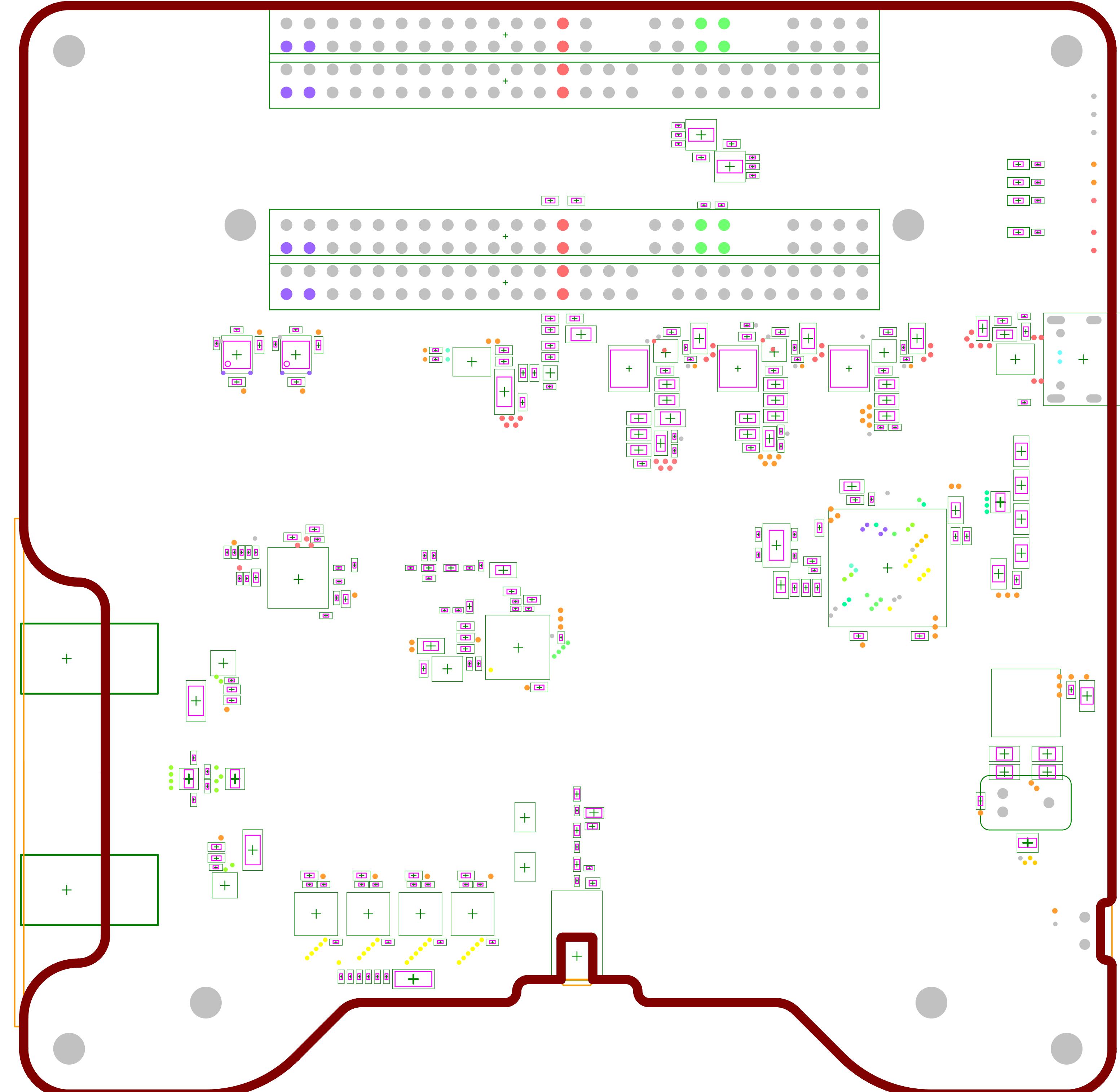
Pluton UPV	
Project: Estigia LoRa Comms PL - mPCIe SoM	
Layer: INT-SIG-2	Dimension
Engineer: Juan Del Pino Mena	
Date: 03/09/2024	Revision: 0.3
	Size: A4

A

B

C

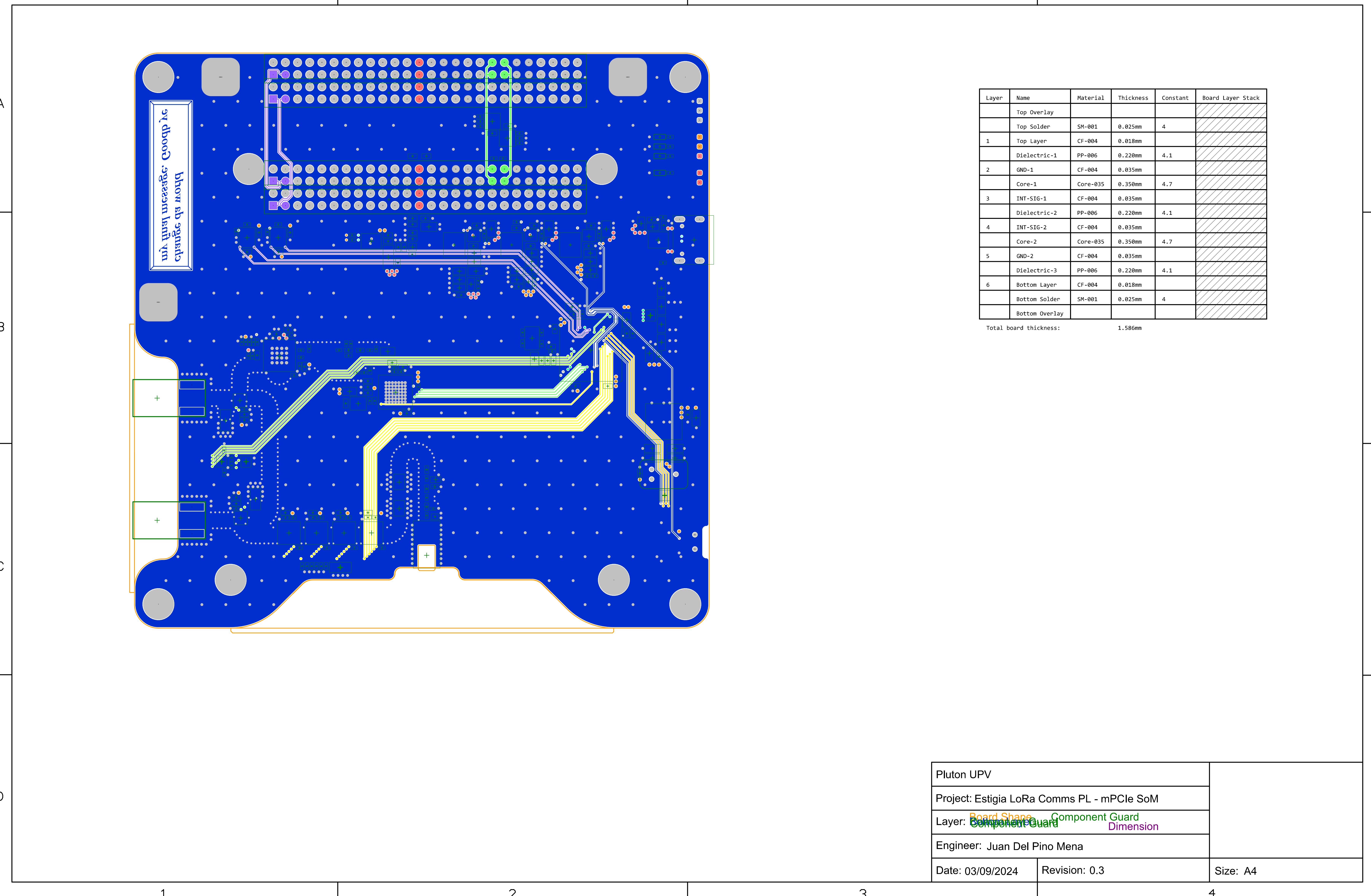
D

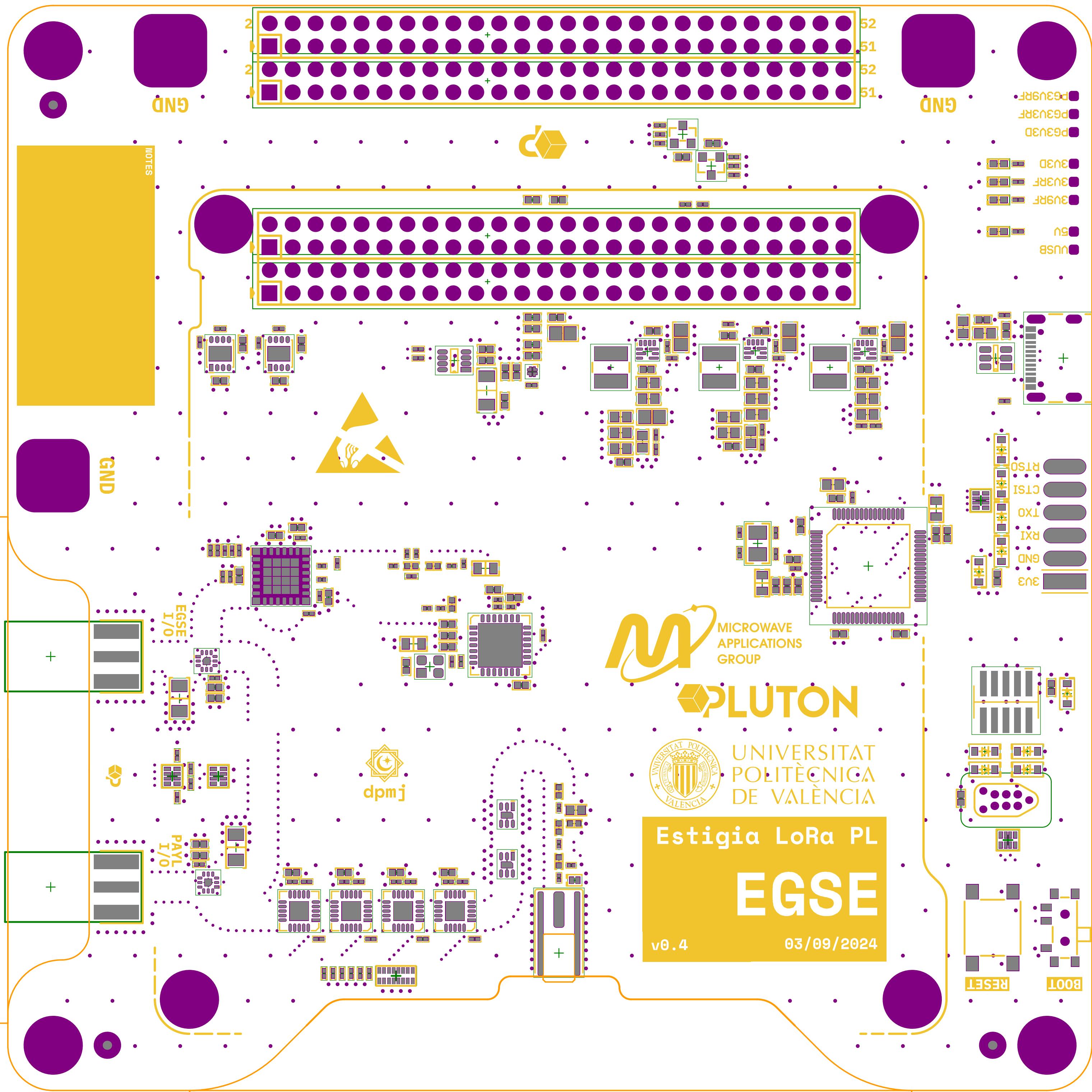


Layer	Name	Material	Thickness	Constant	Board Layer Stack
	Top Overlay				
	Top Solder	SM-001	0.025mm	4	
1	Top Layer	CF-004	0.018mm		
	Dielectric-1	PP-006	0.220mm	4.1	
2	GND-1	CF-004	0.035mm		
	Core-1	Core-035	0.350mm	4.7	
3	INT-SIG-1	CF-004	0.035mm		
	Dielectric-2	PP-006	0.220mm	4.1	
4	INT-SIG-2	CF-004	0.035mm		
	Core-2	Core-035	0.350mm	4.7	
5	GND-2	CF-004	0.035mm		
	Dielectric-3	PP-006	0.220mm	4.1	
6	Bottom Layer	CF-004	0.018mm		
	Bottom Solder	SM-001	0.025mm	4	
	Bottom Overlay				

Total board thickness: 1.586mm

Pluton UPV	
Project: Estigia LoRa Comms PL - mPCIe SoM	
Layer: Component Guard	Board Shape
Component Guard	Dimension
Engineer: Juan Del Pino Mena	
Date: 03/09/2024	Revision: 0.3
	Size: A4

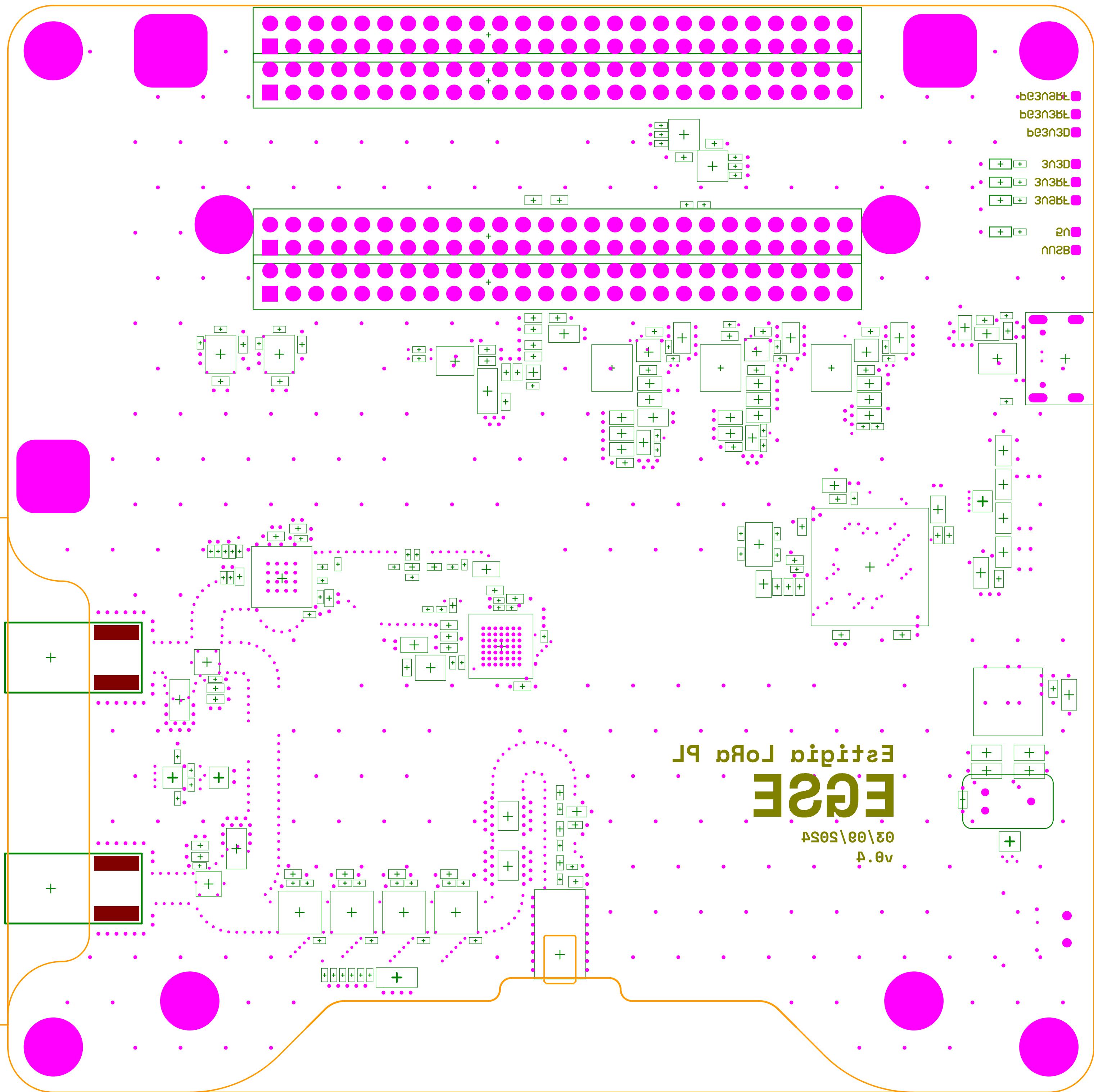




Layer	Name	Material	Thickness	Constant	Board Layer Stack
	Top Overlay				
	Top Solder	SM-001	0.025mm	4	
1	Top Layer	CF-004	0.018mm		
2	Dielectric-1	PP-006	0.220mm	4.1	
3	GND-1	CF-004	0.035mm		
4	Core-1	Core-035	0.350mm	4.7	
5	INT-SIG-1	CF-004	0.035mm		
6	Dielectric-2	PP-006	0.220mm	4.1	
7	INT-SIG-2	CF-004	0.035mm		
8	Core-2	Core-035	0.350mm	4.7	
9	GND-2	CF-004	0.035mm		
10	Dielectric-3	PP-006	0.220mm	4.1	
11	Bottom Layer	CF-004	0.018mm		
12	Bottom Solder	SM-001	0.025mm	4	
13	Bottom Overlay				

Total board thickness: 1.586mm

Pluton UPV	
Project: Estigia LoRa Comms PL - mPCIe SoM	
Layer: Board Shape, Component Guard, Component Guard, Top Dimension	
Engineer: Juan Del Pino Mena	
Date: 03/09/2024	Revision: 0.3
	Size: A4



Layer	Name	Material	Thickness	Constant	Board Layer Stack
	Top Overlay				
	Top Solder	SM-001	0.025mm	4	
1	Top Layer	CF-004	0.018mm		
	Dielectric-1	PP-006	0.220mm	4.1	
2	GND-1	CF-004	0.035mm		
	Core-1	Core-035	0.350mm	4.7	
3	INT-SIG-1	CF-004	0.035mm		
	Dielectric-2	PP-006	0.220mm	4.1	
4	INT-SIG-2	CF-004	0.035mm		
	Core-2	Core-035	0.350mm	4.7	
5	GND-2	CF-004	0.035mm		
	Dielectric-3	PP-006	0.220mm	4.1	
6	Bottom Layer	CF-004	0.018mm		
	Bottom Solder	SM-001	0.025mm	4	
	Bottom Overlay				

Total board thickness: 1.586mm

Pluton UPV	
Project: Estigia LoRa Comms PL - mPCIe SoM	
Layer: Board Shape, Bottom Component Guard, Bottom Paste Guard, Bottom Solder Dimension	
Engineer: Juan Del Pino Mena	
Date: 03/09/2024	Revision: 0.3
	Size: A4

